

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	161	((silicon si epitax\$8) near2 (film layer)) and (substrate wafer fragment support\$6) and (pillar column anchor\$6 post) and ((component element electrode contact terminal) with (fix\$6 mechanical\$6 connect\$6))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/02 09:18
L4	162	(((silicon si epitax\$8) near2 (film layer)) with (pillar column anchor\$6 post)) same (substrate wafer fragment support\$6) same ((component element electrode contact terminal) near4 (fix\$6 mechanical\$6 connect\$6))	US-PGPUB; USPAT	OR	ON	2007/11/02 10:52
L5	189	(((soi sos) not "so") (silicon near (insulator sapphire))) same (body near (tie tied tying contact))	US-PGPUB; USPAT	OR	ON	2007/11/02 11:06
L6	162	(((soi sos) not "so") (silicon near (insulator sapphire))) and (body near (tie tied tying contact))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/02 11:02
L7	60	(((soi sos) not "so") (silicon near (insulator sapphire))) and (body near (tie tied tying contact)) and ((component element electrode contact terminal) with (fix\$6 mechanical\$6 connect\$6))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/02 11:14
L8	53	(((soi sos) not "so") (silicon near (insulator sapphire))) same (body near (tie tied tying contact)) same ((component element electrode contact terminal) with (fix\$6 mechanical\$6 connect\$6))	US-PGPUB; USPAT	OR	ON	2007/11/02 11:36
L9	12309	257/347.ccls. 257/415.ccls. 257/419.ccls. 257/506.ccls. 257/510.ccls. 257/522.ccls. 257/524.ccls. 257/e21.564.ccls. 257/e29.324.ccls. 438/53.ccls. 438/404.ccls. 438/411.ccls. 438/424.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2007/11/02 11:07
L10	73	L9 and (((soi sos) not "so") (silicon near (insulator sapphire))) same (body near (tie tied tying contact)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2007/11/02 11:54

EAST Search History

L11	71	((soi sos) not "so") (silicon near (insulator sapphire))) same (substrate wafer fragment support\$6) same (pillar column anchor\$6 post) same (sti trench groov\$6 recess\$6)	US-PGPUB; USPAT	OR	ON	2007/11/02 12:20
L12	23	((soi sos) not "so") (silicon near (insulator sapphire))) and (substrate wafer fragment support\$6) and (pillar column anchor\$6 post) and (sti trench groov\$6 recess\$6)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/02 12:46
L13	10	9 and (((soi sos) not "so") (silicon near (insulator sapphire))) same (pillar column anchor\$6 post) same (sti trench groov\$6 recess\$6))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2007/11/02 12:58
L14	1	"6272928".pn.	US-PGPUB; USPAT	OR	OFF	2007/11/02 12:59
L15	2	2000gb-0006957.ap,prai.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2007/11/02 12:59
L16	1	2002-113989.NRAN.	DERWENT	OR	OFF	2007/11/02 13:00
S1	3	"6284567".pn. "5780885".pn. "20030173330".pn.	US-PGPUB; USPAT	OR	OFF	2007/11/01 14:03
S2	1	wo-200177009-.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2007/09/20 11:32
S3	1	2002-148886.NRAN.	DERWENT	OR	OFF	2007/09/20 11:33
S4	12309	257/347.cccls. 257/415.cccls. 257/419.cccls. 257/506.cccls. 257/510.cccls. 257/522.cccls. 257/524.cccls. 257/e21.564.cccls. 257/e29.324.cccls. 438/53.cccls. 438/404.cccls. 438/411.cccls. 438/424.cccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2007/11/01 14:27
S5	516	257/522.cccls. 438/411.cccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2007/11/01 16:18

EAST Search History

S6	4555	S4 and (((silicon si epitax\$8) near2 (film layer)) same (substrate wafer fragment support\$6 semiconductor) same (pillar column structure anchor\$6 post))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2007/11/01 16:26
S7	338	S4 and (((silicon si) near2 (film layer)) same (substrate wafer fragment support\$6) same (pillar column anchor\$6 post))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2007/11/01 16:47
S8	2436	((silicon si epitax\$8) near2 (film layer)) and (substrate wafer fragment support\$6 semiconductor) and (pillar column structure anchor\$6 post) and ((component element electrode contact terminal) with (fix\$6 mechanical\$6 connect\$6))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/01 16:28
S10	768	((silicon si epitax\$8) near2 (film layer)) same (substrate wafer fragment support\$6) same (pillar column anchor\$6 post) same ((component element electrode contact terminal) with (fix\$6 mechanical\$6 connect\$6))	US-PGPUB; USPAT	OR	ON	2007/11/02 11:10
S11	544	((silicon si epitax\$8) near2 (film layer)) same (substrate wafer fragment support\$6) same (pillar column anchor\$6 post) same ((component element electrode contact terminal) near4 (fix\$6 mechanical\$6 connect\$6))	US-PGPUB; USPAT	OR	ON	2007/11/01 16:45